

Technical specifications:

- Layers: 1 to 22
- Board thickness: 0.08-3.2mm
- Materials: XPC, FR1, FR-4, CEM-1, CEM-3, high TG, FR4 halogen-free, Rogers
- Minimum line width: 3mil (0.075mm)
- Minimum line spacing: 3mil (0.075mm)
- Maximum panel size: SS-510 x 630mm, DS-558 x 635mm
- Surface finish/treatment: OSP, lead-free HASL, ENIG, gold-plated, immersion tin, immersion silver
- Copper thickness: 0.5-3.0oz
- Solder mask colors: green/yellow/black/white/red/blue • Copper thickness in hole: >25.0um (>1-mil)
- Drilling: 0.2mm PTH: ± 0.08 NPTH: ± 0.05
- Certifications: UL, ISO 9001, ISO 14001, TS16949
- Profiling: punching, routing, V-cut